

Bill of Materials

TI DESIGNS

TIDA-00214

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	Alternate Manufacturer	Package Reference
1	1	!PCB1		Printed Circuit Board	Any	ISE4015	-	-	
2	1	C1	10uF	CAP, CERM, 10uF, 50V, +/-10%, X7R, 1210	MuRata	GRM32ER71H106KA12L			1210
3	2	C2, C7	1.0µF	CAP CER 1UF 50V 10% X7R 0805	Murata Electronics North America	GRM21BR71H105KA12L			0805 (2012 Metric)
4	2	C3, C8	0.1uF	General Purpose Ceramic Capacitors	Venkel	C0805X7R500-104KNE			0805
5	1	C4	68uF	Low ESR Tantalum Capacitors	Venkel	TA020TCR686KER			
6	1	C5	10µF	CAP TANT 10UF 50V 10% 2917	Kemet	T495X106K050ATE300			2917 (7343 Metric)
7	1	C6	10uF	CAP, CERM, 10uF, 6.3V, +/-20%, X5R, 0603	MuRata	GRM188R60J106ME47D			0603
8	1	C11	0.1µF	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Kemet	C0805C104K5RACTU	-	-	0805 (2012 Metric)
9	1	C14	4700 pF	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Novacap	1812B472K202NT	-	-	1812 (4532 metric)
10	1	D1		VCC ON	Lite-On Inc	LTST-S220TBKT			2-SMD, No Lead, Exposed Pad
11	1	D2	1V @ 15mA	DIODE SCHOTTKY 70V 0.07A SOD123F	NXP Semiconductors	BAS70H,115			SOD-123F
12	2	D3, D4	24V	Diode, TVS, Bi, 24V, 350W, SOD-323	Bourns	CDSOD323-T24C-DSL			SOD-323
13	5	J1, J3, J5, J9, J16		Header, TH, 100mil, 3x1, Gold plated, 230 mil above insulator	Samtec	TSW-103-07-G-S			3x1 Header
14	9	J2, J4, J6, J7, J8, J11, J15, J17, J18		Header, TH, 100mil, 4x1, Gold plated, 230 mil above insulator	Samtec	TSW-104-07-G-S			4x1 Header
15	4	J10, J12, J19, J20		Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator	Samtec	TSW-102-07-G-S			2x1 Header
16	2	J13, J14		Samtec Socket Strip 10 POS 2.54mm Thru-Hole	Samtec Inc	SSW-110-23-F-S			
17	1	L1	4.7uH	Inductor, Shielded, Ferrite, 4.7uH, 1.2A, 0.14 ohm, SMD	Coilcraft	EPL3015-472MLB			Inductor, 3x1.55x3mm
18	1	R1	1.8Meg	RES, 1.8Meg ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04021M80JNED			0402
19	1	R2	220	RES, 220 ohm, 5%, 0.125W, 0805	Panasonic	ERJ-6GEYJ221V			0805
20	1	R3	200k	RES, 200k ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW0402200KJNED			0402
21	3	R4, R9, R13	0.0	RES 0.0 OHM 1/8W JUMP 0805	Yageo	RC0805JR-070RL			0805 (2012 Metric)
22	4	R5, R6, R16, R17	4.7k	RES, xxx ohm, x%, xW,	Yageo	RT0603FRE074K7L	-	-	0603 (1608 Metric)
23	2	R8, R12	10	RES, xxx ohm, x%, xW,	Vishay Dale	CRCW060310R0FKEAH	-	-	0603 (1608 Metric)
24	1	R10	121 Ohm	RES 121 OHM 0.1W 1% 0805	Venkel	CR0805-10W-1210FT			0805 (2012 Metric)
25	1	R18	1M	RES, xxx ohm, x%, xW,	Ohmite	HVC2512T1004JET	-	-	2512 (6432 Metric)
26	5	SH-J1, SH-J10, SH-J12, SH-J13	1x2	Shunt, 100mil, Gold plated, Black	Samtec	SNT-100-BK-G	969102-0000-DA	3M	Shunt

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27	2	TB1, TB2		CONN TERM BLOCK 2.54MM	Phoenix Contact	1725669			
28	1	U1		LOW INPUT VOLTAGE STEP-UP	Texas Instruments	TPS61220DCK		None	DCK0006A
29	1	U2		Extended Common-Mode RS-485	Texas Instruments	SN65HVD24D		None	D0008A
30	0	C9	68uF	Low ESR Tantalum Capacitors	Venkel	TA020TCR686KER			
31	0	C10	10uF	CAP TANT 10UF 50V 10% 2917	Kemet	T495X106K050ATE300			2917 (7343 Metric)
32	0	C12, C13, C15, C16	1.0uF	CAP CER 1UF 50V 10% X7R	Murata Electronics Nor	GRM21BR71H105KA12			0805 (2012 Metric)
33	0	FID1, FID2, FID3, FID4,		Fiducial mark. There is nothing to	N/A	N/A			Fiducial
34	0	R7, R14	0.0	RES 0.0 OHM 1/8W JUMP 0805	Yageo	RC0805JR-070RL			0805 (2012 Metric)
35	0	R11, R19, R21	49.9 Ohm	RES 49.9 OHM 0.1W 1% 0805	Venkel	CR0805-10W-49R9FT			0805 (2012 Metric)

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